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				218251US6X PCT	based on PCT/FR00/02065			
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT Philippe ROBERT				
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				U.S. PATENT DOCUMENTS	·			
EXAMINER		DOCUMENT		U.S. PATENT DOCUMENTS	T	SUB	EII I	NG DATE
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	itial if r	eference is considered, v	hether or no	t citation is in conformance with MPEP 6 with next communication to applicant.	09; Draw li			